

<b>PCN Number:</b>	20210706003.1.1		<b>PCN Date:</b>	July 07, 2021																
<b>Title:</b>	Qualification of TIPI as an additional Assembly and Test site for select devices																			
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services																	
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Oct 07, 2021	<b>Estimated Sample Availability:</b>	Date Provided at Sample request																	
<b>Change Type:</b>																				
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site															
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material															
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process															
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site															
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials															
				<input type="checkbox"/>	Wafer Fab Process															
<b>PCN Details</b>																				
<b>Description of Change:</b>																				
Texas Instruments Incorporated is announcing the qualification TIPI (TI Philippines Inc.) as Additional Assembly Site for select devices listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.																				
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin</th> <th>Assembly Country Code</th> <th>Assembly Site City</th> </tr> </thead> <tbody> <tr> <td>HANA</td> <td>HNT</td> <td>THA</td> <td>Ayutthaya</td> </tr> <tr> <td>JCET</td> <td>JCE</td> <td>CHN</td> <td>Jiangyin</td> </tr> <tr> <td>TIPI</td> <td>PHI</td> <td>PHL</td> <td>Baguio City</td> </tr> </tbody> </table>					Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City	HANA	HNT	THA	Ayutthaya	JCET	JCE	CHN	Jiangyin	TIPI	PHI	PHL	Baguio City
Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City																	
HANA	HNT	THA	Ayutthaya																	
JCET	JCE	CHN	Jiangyin																	
TIPI	PHI	PHL	Baguio City																	
<b>Material Differences:</b>																				
	<b>HANA</b>	<b>JCET</b>	<b>TIPI</b>																	
Mount compound	400194	120402001600	4226215																	
Mold compound	450214	111020003809	4222198																	
<b>Reason for Change:</b>																				
Continuity of supply.																				
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>																				
None																				
<b>Anticipated impact on Material Declaration</b>																				
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <a href="#">TI Eco-Info website</a> . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.																	
<b>Changes to product identification resulting from this PCN:</b>																				

Assembly Site		
HANA	Assembly Site Origin (22L)	ASO: HNT
JCET	Assembly Site Origin (22L)	ASO: JCE
TIPI	Assembly Site Origin (22L)	ASO: PHI

Sample product shipping label (not actual product label)



**TEXAS INSTRUMENTS**  
 MADE IN: Malaysia  
 2DC: 2d:  
 MSL 2 /260C/1 YEAR SEAL DT  
 MSL 1 /235C/UNLIM 03/29/04  
 OPT:  
 ITEM: 39  
**LBL: 5A (L)T0:1750**

(1P) SN74LS07NSR  
 (Q) 2000 (D) 0336  
 (31T) LOT: 3959047MLA  
 (4W) TKY (1T) 7523483SI2  
 (P)  
 (2P) REV: (V) 0033317  
 (20L) CSO: SHE (21L) CCO:USA  
 (22L) ASO: MLA (23L) ACO: MYS

**Product Affected:**

SN1511004DRLR	TMP102AIDRLT	TMP112BIDRLT	TMP302BDRLR-P
SN1511004DRLT	TMP102BIDRLR	TMP112NAIDRLR	TMP302BDRLT
SN1608035DRLR	TMP102BIDRLT	TMP112NAIDRLT	TMP302CDRLR
SN1710027DRLR	TMP112AIDRLR	TMP302ADRLR	TMP302CDRLT
SN1710027DRLT	TMP112AIDRLT	TMP302ADRLT	TMP302DDRLR
TMP102AIDRLR	TMP112BIDRLR	TMP302BDRLR	TMP302DDRLT

## Qualification Report

Approve Date 17-Jun-2021

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TMP102AIDRLR	Qual Device: TMP112AIDRLR	Qual Device: TMP302ADRLR
PC	PreCon Level 1	MSL1-260C	3/924/0	-	-
HTOL	High Temp Operating Life, 125C	1000 Hours	1/77/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	-	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0	-	-
TC	Temperature Cycle, -65/150C	1000 Cycles	3/231/0	-	-
HTSL	High Temp Storage Bake 150C	1000 Hours	1/77/0	-	-
MSL	Moisture Sensitivity	MSL1-260C	3/36/0	-	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	1/30/0
YLD	Yield Evaluation	(per mfg. Site specification)	Pass	-	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	3/pass	-	-

- QBS: Qual By Similarity
- Qual Device TMP112AIDRLR is qualified at LEVEL1-260C
- Qual Device TMP302ADRLR is qualified at LEVEL1-260C
- Qual Device TMP102AIDRLR is qualified at LEVEL1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles  
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/Green/Pb-free>Status>:  
Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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